ASME InterPACK 2022

International Technical Conference on Packaging and Integration of Electronic and Photonic Microsystems

Conference: October 25 – 27, 2022
The Hyatt Regency Orange County, Garden Grove, CA

Since 1992, InterPACK has been a premier international conference for the exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronics packaging and heterogeneous integration. It is the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). InterPACK is a systems-focused conference covering topics on Heterogeneous Integration, Servers of the Future, Edge and Cloud Computing, Internet of Things, Additive Printed Electronics, Flexible and Wearable Electronics, Photonics and Optics, Power Electronics, Energy Conversion and Storage, and Autonomous, Hybrid and Electric Vehicles. The international nature of the meeting has been highly beneficial in promoting global interactions between industry, academia, research institutions, funding agencies, start-ups and entrepreneurs. In addition to paper presentations and exhibits, InterPACK 2022 will include panel discussions, workshops, tutorials, keynote and technology talks by prominent speakers, and a joint industry, national laboratory, and academia poster session

Plenary Speakers

Thomas Kazior
Program Manager
DARPA

Philseok Kim
Program Director
ARPA-E

Abhinav Saxena
Principal Scientist
GE Research

Mark Spector
Program Officer
ONR

Ivor Barber
VP of Packaging
AMD

Workshop dedicated to CHIPS and Science act

If you are interested in how the CHIPS and Science Act will strengthen domestic semiconductor manufacturing, design and research, join ASME InterPACK and get the latest news from industry and academia representatives

More information about ASME InterPACK 2022 you can find here:

http://event.asme.org/interpack

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Technical Tracks

Heterogeneous Integrated Systems ▪ Advanced packaging ▪ Die stacking ▪ Multichip modules ▪ Through-silicon vias (TSV) ▪ System in package (SiP)	Multi-scale Thermal Transport, Thermal Materials, and Energy Systems ▪ 1D and 2D nanomaterials ▪ Nano-scale conjugate heat transfer ▪ Renewable energy ▪ Energy storage ▪ Multi-scale energy transport
Data Centers, Servers of the Future, Edge and Cloud Computing ▪ Thermal and infrastructure management ▪ Rack level cooling ▪ Hardware thermal management ▪ Thermal interface materials ▪ Advanced cooling technologies	Harsh Environment Electronic Applications for Transportation Systems ▪ High temperature sensors ▪ RADAR ▪ Advanced driver assistance system ▪ MEMS packaging ▪ Nano-satellites
Flexible, Wearable and Additively Printed Electronics ▪ Printed & additive multi-layer electronics ▪ Wearables ▪ Internet of things (IoT) ▪ Flexible electronics for automotive, space, and RF applications	Reliability of Electronic Packages and Systems ▪ Packaging reliability ▪ Electromigration ▪ Reliability of power electronics packaging ▪ Reliability testing for harsh environment ▪ Reliability modeling and simulation
Photonics and Optics ▪ Photonics packaging ▪ Optical integration ▪ Thermal/mechanical challenges ▪ LED Systems ▪ High speed transceivers	Digital Technologies in Microelectronics ▪ Exaflop computing systems ▪ Artificial intelligence (AI) ▪ Machine learning (ML) ▪ Digital twin ▪ Quantum computing
Power Electronics ▪ Wide bandgap electronic devices ▪ Solid state technologies ▪ Multi-physics co-design ▪ Thermal management and packaging ▪ Harsh environment sensors	Interactive Presentations ▪ Industry networking ▪ Showcase leading-edge technologies ▪ Direct feedback from professionals ▪ Industry mentorship ▪ Best poster award competition

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Tutorials, Workshops and Keynote Speakers

Topic	Speaker
Nanophotonic Systems: Novel Nanophononics Device and Future Applications in Electronics *(Tutorial)* *Organized By:* **Anil Yuksel**, *IBM Corp.*	**Jason Valentine,** *Vanderbilt University*
Advance Liquid-Cooling Technology for ICT: Performance and Economic Benefits *(Tutorial)* *Organized By:* **Roanld Warzoha**, *US Naval Academy*	**Raffaele-Luca Amalfi** , *Seguente Tech.*
Optimization of Battery Recycling for Sustainability *(Tutorial)* *Organized By:* **Nenad Miljkovic**, *UIUC.*	**Ilias Belharouak,** *Oak Ridge National Lab.* **Zheng Chen,** *UC -San Diego*
Introduction to Robotics, AI, and Intel's OpenVINO Toolkit *(Workshop)* *Workshop Organized By:* **Anna Prakash,** *Intel Corp.*	**Anna Prakash,** *Intel Corp.* **Christine Stewart,** *Intel Corp.*
Managing Data Center Challenges in the Age of AI *(Keynote)* *Organized By:* **Gamal Refai-Ahmed,** *AMD*	**Ali Heydari,** *Nvidia*
Novel ZTACH ACE: Anisotropic Conductive Epoxy for High-Volume *(Keynote)* *Organized By:* **Benjamin Leever,** *Air Force Research Lab.*	**John Yundt,** *Sunray Scientific*
Form and Function in Power Electronics: Driving Progress in Efficient Energy Conversion by Matched Technology-Topology Integrated Design *(Keynote)* *Organized By:* **Gilbert Moreno,** *NREL and* ***Emre Gurpinar,*** *Siskorsky Aircraft*	**Prof. Alberto Castellazzi,** *Kyoto University of Advanced Science*
Past and Future of Reliability Assessment of Electronic Materials *(Keynote)* *Organized By:* **Pradeep Sharma,** *Univ. of Houston*	**Patrick McCluskey,** *Univ. of Maryland*
Building Explainable AI for Enterprise *(Keynote)* *Organized By:* **Azeem Sarwar,** *General Motors*	**Krishna Gade**, *Fiddler AI*

More information about keynotes for ASME InterPACK 2022 can be fond here: https://event.asme.org/InterPACK/Speakers/Track-Keynotes

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Panel Discussions

Panel Topic	Panelist
Impact of Sustainability Goals on Future Hardware and Data Center *Organized By:* ***Cheng Chen****, Meta Inc.*	**Tiffany Jin,** *Meta Inc.* **Jimil Shah,** *TMGcore* **Peter de Bock,** *Dept. of Energy.* **Pritish Parida,** *IBM* **Ali Heydari,** Nvidia
Pathfinding to Maximize System Performance *Organized By:* **Gamal Refai-Ahmed**, *XILINX Corp.*	**Mr. Ivor Barber,** *AMD* **Prof. Bahagat Sammakia,** *SUNY Binghamton* **Ravi Mahajan,** *Intel* **Prof. Al Ortega,** *Villanova University*
Hybrid and System Level Integration for Electronics Packaging *Organized By:* **Benjamin Leever**, *US Air Force.*	**Nancy Stoffel,** *GE Global Research* **Mark Poliks,** *SUNY Binghamton* **Jaim Nulman,** *Nanodimension Inc* **Suresh Sitaraman,** *Georgia Tech*
The Importance of Sustainable Energy Systems *Organized By:* **Luca Amalfi** *, Seguente Tech.*	**Prof. Nenad Miljkovic,** *UIUC* **Filippo Cataldo,** *Wieland Provides* **Cosimo Pecchioli,** *Alpha Laval* **Prof. Aaron Wemhoff,** *Villanova Univ.*
Thermal and Mechanical Challenges and Opportunities of Advanced Mobile/Telecom/IoT/Auto/Computing Devices *Organized By:* **Victor Chiriac**, *GCTG LLC.*	**Sreekant Narumanchi ,** *NREL* **Raffaele Luca Amalfi** *,Seguente Tech.* **Prof. Amy Marconnet ,** *Purdue* **Sam Zhao,** *Broadcom* **Christopher Kapusta,** *GE Research* **Kinzy Jones**, *Google Inc*
Reliability of Additively Manufactured Electronics *Organized By:* **Patrick McCluskey**, *U. of Maryland.*	**Prof. David Huitink**, *U. of Arkansas* **Prof. Abhijit Dasgupta**, *U. of Maryland* **Prof. Siddhartha Das**, *U. of Maryland*
Women in Engineering *Organized By:* **Anna Prakash**, *Intel Corp.*	*To be confirmed*
Why AI/Data Science Projects Fail *Organized By:* **Azeem Sarwar**, *General Motors*	**Joyce Weiner,** *Intel* **Taimoor Khawaja,** *Cox Communications* **Syed Usman Ali,** *Bloomberg* **Krishna Gede,** *Fiddler AI*
Heterogeneous Integration *Organized By:* ***Ravi Mahajan***, *Intel Corp (to be confirmed)*	*To be confirmed*

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SETTING THE STANDARD